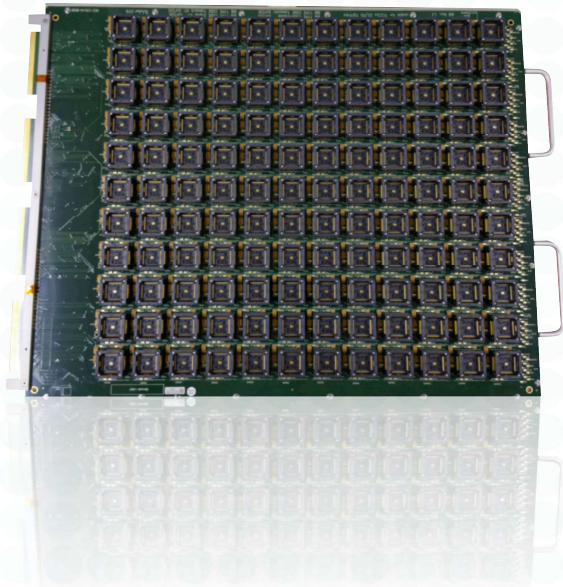


# BURN-IN BOARD

FOR HIGH POWER DEVICES

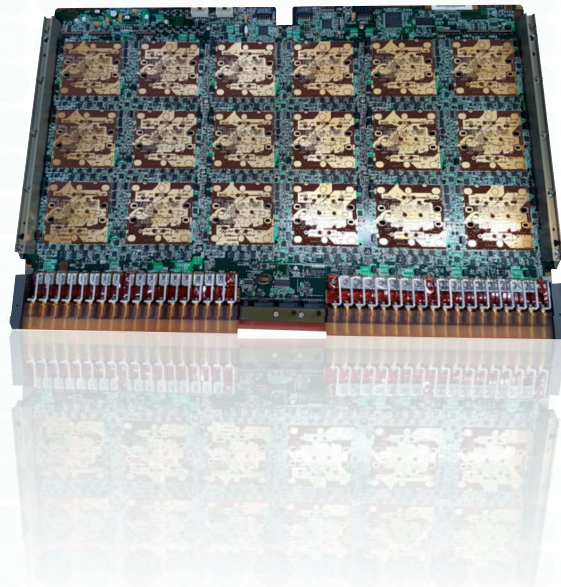
BIG FORM FACTOR BOARD WITH SOCKET OPTIMIZATION



- High Power Devices Up To 200W/DUT
- 1.6 kW Per Board
- 16 – 20 Layers
- Small Via – 9 mils

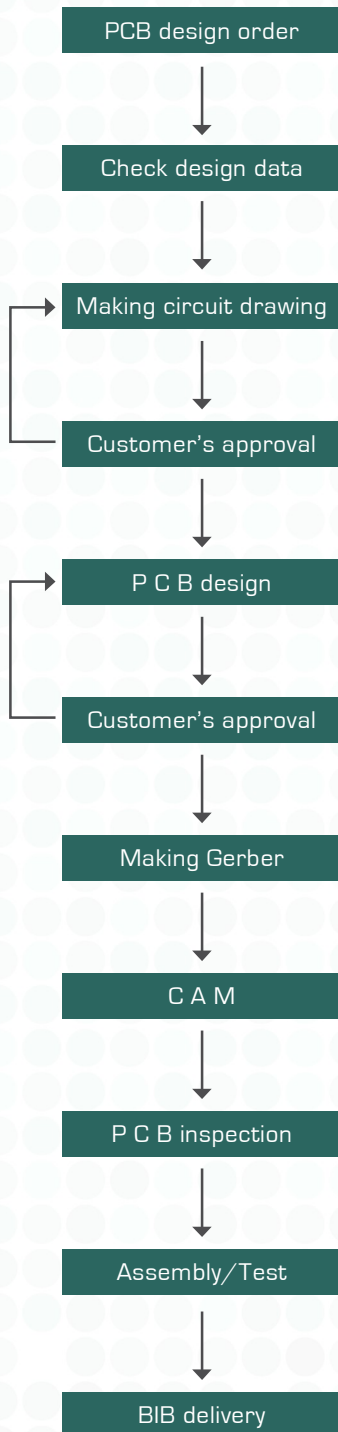
Designed & built for:

- BGA
- QFP
- QFN
- TQFP
- LQFP
- LFBGA
- Socket type with 0.4mm pitch



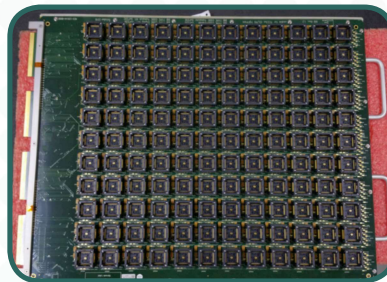
KES designs and manufactures high performance burn-in boards for use during burn-in and testing of a wide variety of high-power semiconductors. Each burn-in board is designed by our technical specialists and manufactured to meet customer's specifications.

# SPECIFICATIONS

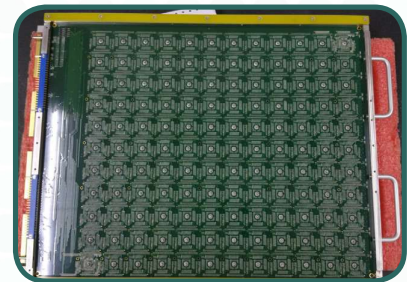


- High power devices: 200W/DUT up to 1.6 kW per board
- Socket Type: BGA/LGA/FCBGA/FCLGA down to 0.4mm pitch
- High Pin Count > 2000 pins
- Layers: 16 layer [4 oz] / 20 layer [2 oz]
- Discrete BGA power module
- Skew rate control
- Small via [9 mil] with high aspect ratio: single drill

Top Side



Bottom Side



Board Thickness : 64mils (1.6mm)  
Board Size : 570mm [L] x 440mm [W]

Top Side



Bottom Side



Board Size : 22.972" [L] x 13.877" [W]  
Board Thickness : 125mils (3.2mm)

- Fastest leadtime
- Highest quality
- Competitive pricing

For more information, please contact:-



KES SYSTEMS & SERVICE (1993) PTE LTD  
1093 Lower Delta Road  
#02-01, Singapore 169204

**Tel:** (65) 62725842 | **Fax:** (65) 62735107 | **Email:** sales@sunright.com